

Final Product/Process Change Notification Document #: FPCN21497ZE

Issue Date: 28 March 2018

Title of Change:	Transfer of Assembly and Test operations of SMB packaged products to On Semiconductor Vietnam (OSV).		
Proposed Changed Material First Ship Date:	1 May 2019		
Current Material Last Order Date:	1 February 2019 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date w be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date:	30 April 2019 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.		
Product Category:	Active components – Discrete components		
Contact information:	Contact your local ON Semiconductor Sales Office or < Phuong.Hoang@onsemi.com >		
Samples:	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.		
Sample Availability Date:	30 February 2018		
PPAP Availability Date: 45 ngày	30 February 2018		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < cheanching.sim@onsemi.com >.		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>		
Change Category:	Type of Change		
Process – Assembly	Move of all or part of assembly to a different location/site/subcontractor.		
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor		
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.		

Description and Purpose:

This Final Notification announces the transfer of Assembly and Test of SMB products from ON Semiconductor Malaysia (SBN) to ON Semiconductor Vietnam (OSV).

The Constant Current Regulator (CCR) products in SMB package are currently being assembled and tested at Seremban. Upon the expiration of this FPCN, Constant Current Regulator (CCR) products in SMB package will be processed at OSV location using same Bill of Material.

ON Semiconductor Vietnam (OSV) is qualified site for SMB Standard discrete packaged products and is ISO TS16949 certified.

Products sourced from OSV have been qualified to Automotive requirements and continue remain as Pb-free, Halide free and RoHS compliant.

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Reason / Motivation for Change:	Change benefits for customer(s): Unconstrained Automotive Sourcing; Mfg floor space for future expansion Sustained TS16949 Certification with the Same BOM / Equipment / Processes Allow for increased support for Seremban packages that are currently constrained OSV has been audited to VDA6.3 Risks for delayed conversion: No Seremban supply after April 30, 2019 Limited ability to support bridge build availability.		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.		
Sites Affected:	ON Semiconductor Sites: ON Seremban, Malaysia ON Dong Nai Province, Vietnam	External Foundry/Subcon Sites: None	
Marking of Parts/ Traceability of Change:	Product from ON Semiconductor Vietnam (OSV) will be marked with site code "VN" prior to the date code while the Seremban device does not have site code marking.		

Reliability Data Summary:

QV DEVICE NAME: NSVC2050JBT3G (CCR)

PACKAGE: SMB

Test	Specification	Condition	Interval	Result
HTOL	JESD22-A108	Ta = 125°C, Tj(est) = 175°C	1008 hrs	0/252
HTSL	JESD22-A103	Ta = 175 °C	1008 hrs	0/252
TC	JESD22-A104	Temp = -65°C to +150°C 1000 cyc		0/252
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased 96 hrs		0/252
PC	J-STD-020 JESD- A113	MSL 1 @ 260 °C		0/504
RSH	JESD22- B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45

Note: AEC-1 pager is attached.

To access file attachments on pdf copy of PCN, please be guided by the steps below:

- 1. Download pdf copy of the PCN to your computer
- $2.\ Open\ the\ downloaded\ pdf\ copy\ of\ the\ PCN$
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachm ent field
- 4. Then click on the attached file/s

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Electrical Characteristic Summary:					
Electrical characteristics are not impacted.					
List of Affected Standard Parts:					
Current Part Number	Qualification Vehicle				
NSVC2020JBT3G	NSVC2050JBT3G				
NSVC2030JBT3G					
NSVC2050JBT3G					

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Appendix A: Changed Products

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Product	Customer Part Number	New Part Number	Qualification Vehicle
NSVC2020JBT3G		NA	NSVC2050JBT3G
NSVC2030JBT3G		NA	NSVC2050JBT3G
NSVC2050JBT3G		NA	NSVC2050JBT3G